



3D BGA STEREO VISION PATENTS AWARDED

Wednesday July 5, 2000, 1:00 pm Eastern Time

Elwin M. Beaty, President of Scanner Technologies Corporation, announced today the award of two patents for its 3D BGA stereo vision inspection equipment. Patent numbers 6,064,756 and 6,064,757 relate to the three dimensional inspection of BGA, CSP and bump on wafer products. Mr. Beaty stated that the UltraVim Plus product line incorporating this technology has been responsible for achieving record sales and profits. Mr. Beaty further stated that these two patents establish Scanner Technologies as the world leader in the development of stereo vision based 3D inspection technology for ball and bump devices.